Call for Papers

The IEEE Electrical Design of Advanced Packaging and Systems (EDAPS) Symposium is the premier international conference in Asia-Pacific region to share the recent progress of design, modeling, simulation and measurement related to the electrical issues arising at the chip, package and system levels. Covering the paper presentations, industry exhibitions, workshops and tutorials, the EDAPS 2020 will be held **virtually from December 14 to 16, 2020**. The technical program of the symposium not only addresses the current technical issues but also brings out the topics on IC design, SiP/SoP packaging, EMI/EMC, EDA tools and most importantly the challenge issues in advanced 3D-IC and TSV design. For further information, please visit the website at to edaps.org.

Manuscript Submission Deadline: October 23, 2020
Notification of Acceptance: November 6, 2020

Topics

- 3D-Ics / TSVs / Interposers
- Testing on 3D-IC and SiP
- Signal, Power and Thermal Integrity
- Multi-physics Simulation Techniques
- Design and Modeling for High-speed Channels
- Electronic Packages, SiP / SoP
- IC and Package Level EMC
- RF/mm-wave Packages
- Embedded Passives
- Power Electronic Packages
- Advanced Simulation Tools and CAD
- Electrical Design of Flexible Devices and Sensing
- Electrical Design for 5G Wireless Communication
- Substrate Technology for Packages and PCBs
- 2-D Materials for 3D-ICs and SiP

Awards

- Best Paper Award
- Best Student Paper Award
- Best Poster Award

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Conference Information

- Web Site: edaps.org
- Contact: admin@edaps.org

PAPER SUBMISSION

Papers should be submitted electronically in two-column and three-page PDF file format through the EDAPS website (www.edaps.org). A Microsoft Word template is available on the symposium website. Hardcopy submissions will NOT be accepted. Submitted manuscripts should be camera ready and compliant with the general standards of the IEEE, including appropriate referencing. Non-compliant manuscripts will not be considered for review. In addition, authors of accepted papers will be invited to submit an extended version of their manuscript for a Special Section based on EDAPS-2020 to be published in the IEEE Transactions on components, packaging and manufacturing technology (T-CPMT).